SEIKO EPSON CORPORATION

SAW Resonator FS-585

Product name	FS-585 315.031000MHz 99.0 +50.0-50.0
Product Number / Ordering code	Q25FS58500005xx

Please refer to the 5.Packing information about xx (last 2 digits)

Pb free / Complies with EU RoHS directive
Reference weight Typ. 112 mg

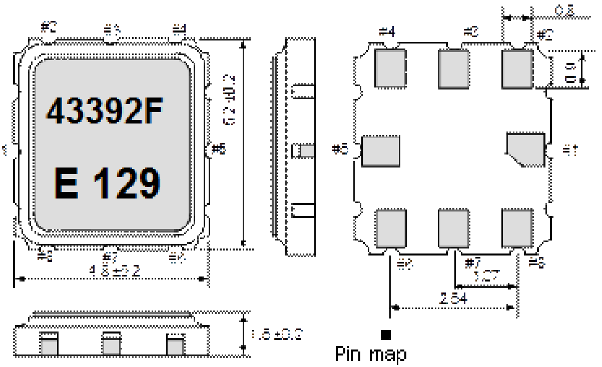
1.Absolute maximum ratings

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Remarks
Storage temperature	T_stg	-40	-	125	ºC	-
Maximum drive level	GL	-	-	10.0	mW	Suppose to be undestroyed

2.Specificatoins(characteristics)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Remarks
Nominal frequency	f_nom		315.031		MHz	
Operating temperature	T_use	-40	-	120	ºC	-
Level of drive	DL	-	2	-	mW	-
Frequency tolerance	f_tol	-50	-	50	x 10^{-6}	-
Turnover temperature	Ti	30	40	50	ºC	-
Parabolic coefficient	B	-	-3.4		x 10^{-8}/ºC^2	-
Motional resistance (ESR)	R1	-	-	18	Ω	T_use= +25degC
Motional capacitance	C1	-	2.1	-	fF	315MHz
Shunt capacitance	C0	-	3.1	-	pF	315MHz
Motional inductance	L1	-	TBD	-	mH	-
Inharmonic spurious	RS/R1	R1 x 2	-	-		-
Frequency aging	f_age	-10	-	10	x10^{-6} /yea	T_use= +25degC

3.External dimensions (Unit: mm)

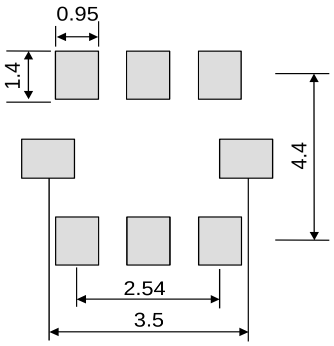


#1,#2,#5,#6 are connected to the cover.

Pin map

Pin	Connection
3,7	IN, OUT
4,8	N.C.
1,2,5,6	GND

4.Footprint(Recommended) (Unit: mm)



5.Packing information

[1]Product number last 2 digits code (xx) description The recommended code is "00"

Q25FS58500005xx

Code	Condition	Code	Condition
01	Any Q'ty vinyl bag(Tape cut)	14	1000pcs / Reel
11	Any Q'ty / Reel	15	2000pcs / Reel
12	250pcs / Reel	16	3000pcs / Reel
13	500pcs / Reel	00	4000pcs / Reel

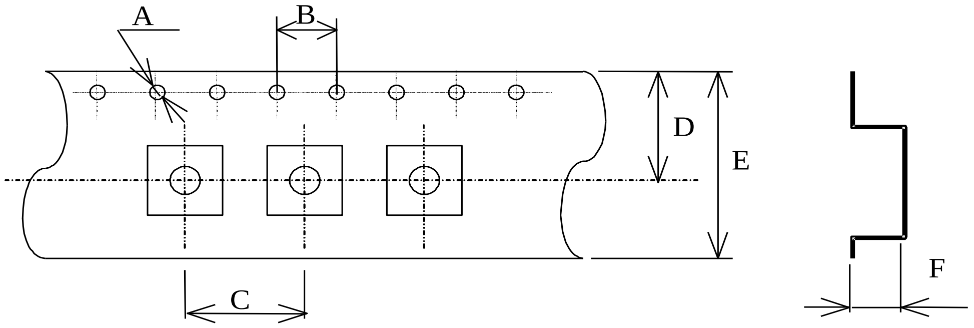
[2] Taping specification

Subject to EIA-481 & IEC-60286

(1) Tape dimensions

Material of the Carrier Tape : PS
Material of the Top Tape : PET+PE

Unit: mm

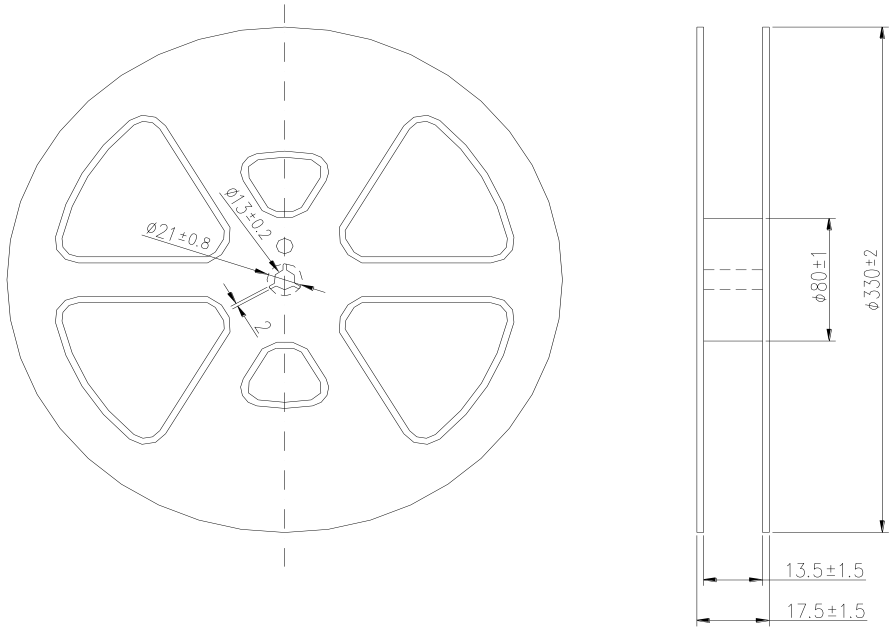


Symbol	A	B	C	D	E	F
FF-555	Φ1.5	4	8	7.25	12	1.7

(2) Reel dimensions

Material of the Reel : PS

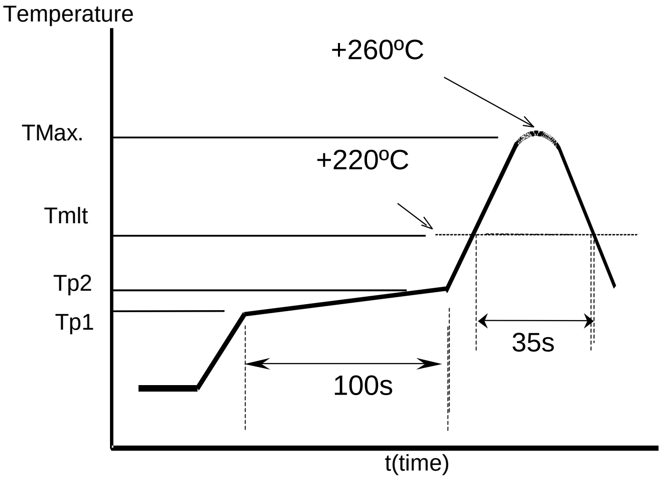
Unit: mm



6.Reflow profile

Pre Heating Temperature
Tp1 ~ Tp2 = + 170 °C
Heating Temperature
TMlt = + 220 °C
Peek Temperature
TMax. = + 260 °C

Point of measuring
In case of Solder ability
Terminal.
In case of Resistance to soldering heat
Surface.



7.Notice

- This material is subject to change without notice.
- Any part of this material may not be reproduced or duplicated in any form or any means without the written permission of Seiko Epson.
- The information about applied circuitry, software, usage, etc. written in this material is intended for reference only. Seiko Epson does not assume any liability for the occurrence of infringing on any patent or copyright of a third party. This material does not authorize the licensing for any patent or intellectual copyrights.
- When exporting the products or technology described in this material, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations.
- You are requested not to use the products (and any technical information furnished, if any) for the development and/or manufacture of weapon of mass destruction or for other military purposes. You are also requested that you would not make the products available to any third party who may use the products for such prohibited purposes.
- These products are intended for general use in electronic equipment. When using them in specific applications that require extremely high reliability, such as the applications stated below, you must obtain permission from Seiko Epson in advance.
  / Space equipment (artificial satellites, rockets, etc.)
  / Transportation vehicles and related (automobiles, aircraft, trains, vessels, etc.)
  / Medical instruments to sustain life
  / Submarine transmitters
  / Power stations and related
  / Fire work equipment and security equipment
  / Traffic control equipment
  / And others requiring equivalent reliability.

- All brands or product names mentioned herein are trademarks and/or registered trademarks of their respective.

8.Contact us

http://www5.epsondevice.com/en/contact/